

AO7415
P-Channel Enhancement Mode Field Effect Transistor

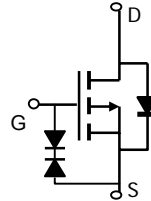
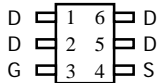
General Description

The AO7415 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge, and operation with gate voltages as low as 2.5V, in the small SOT363 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters. It is ESD protected to 2KV HBM. *Standard product AO7415 is Pb-free (meets ROHS & Sony 259 specifications). AO7415L is a Green Product ordering option. AO7415 and AO7415L are electrically identical.*

Features

$V_{DS} (V) = -20V$
 $I_D = -2A (V_{GS} = -10V)$
 $R_{DS(ON)} < 100m\Omega (V_{GS} = -10V)$
 $R_{DS(ON)} < 125m\Omega (V_{GS} = -4.5V)$
 $R_{DS(ON)} < 170m\Omega (V_{GS} = -2.5V)$

SC-70-6
(SOT-363)
Top View


Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	I_D	$T_A=25^\circ C$	-2
		$T_A=70^\circ C$	-1.6
Pulsed Drain Current ^B	I_{DM}	-8	A
Power Dissipation ^A	P_D	$T_A=25^\circ C$	0.625
		$T_A=70^\circ C$	0.4
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	$t \leq 10s$	160	$^\circ C/W$
Maximum Junction-to-Ambient ^A		Steady-State	180	$^\circ C/W$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	130	160	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-16\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-0.5 -2.5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 10\text{V}$ $V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			± 1 ± 10	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.7	-0.9	-1.4	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-4.5\text{V}$, $V_{DS}=-5\text{V}$	-15			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-2\text{A}$		80	100	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		115		
		$V_{GS}=-4.5\text{V}$, $I_D=-1.3\text{A}$		98	125	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$, $I_D=-1.0\text{A}$		130	170	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-2\text{A}$		5		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.84	-0.95	V
I_S	Maximum Body-Diode Continuous Current				0.6	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-10\text{V}$, $f=1\text{MHz}$		512	620	pF
C_{oss}	Output Capacitance			77		pF
C_{rss}	Reverse Transfer Capacitance			62		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		9.2	13	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-4.5\text{V}$, $V_{DS}=-10\text{V}$, $I_D=-2\text{A}$		4.9	6	nC
Q_{gs}	Gate Source Charge			3.5		nC
Q_{gd}	Gate Drain Charge			3.7		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-4.5\text{V}$, $V_{DS}=-10\text{V}$, $R_L=5\Omega$, $R_{GEN}=3\Omega$		11	13	ns
t_r	Turn-On Rise Time			8	10	ns
$t_{D(off)}$	Turn-Off DelayTime			34	41	ns
t_f	Turn-Off Fall Time			12	15	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-2\text{A}$, $di/dt=100\text{A}/\mu\text{s}$		13	17	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-2\text{A}$, $di/dt=100\text{A}/\mu\text{s}$		4	6	nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any a given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating. Rev2: August 2005

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

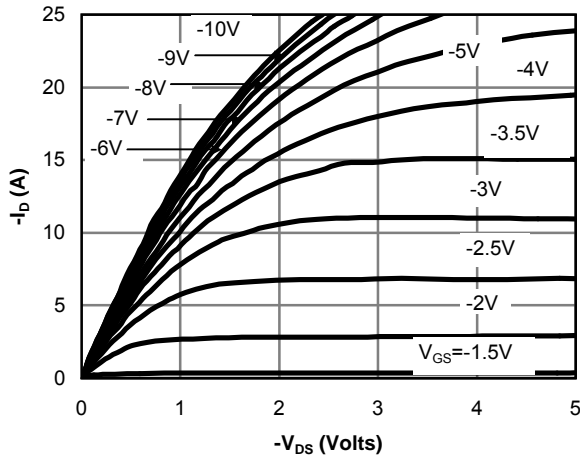


Fig 1: On-Region Characteristics

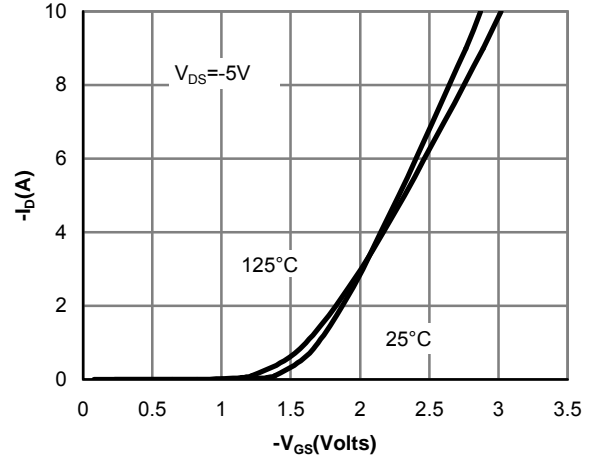


Figure 2: Transfer Characteristics

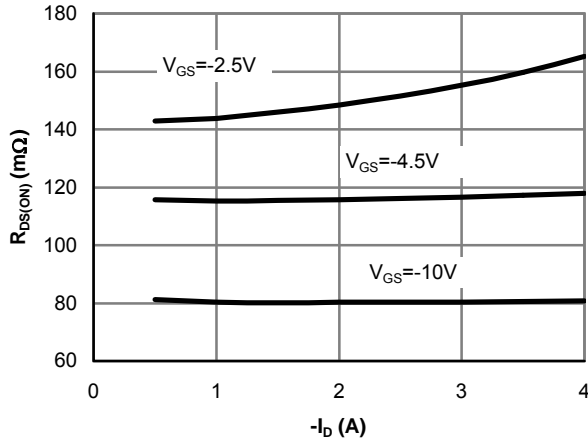


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

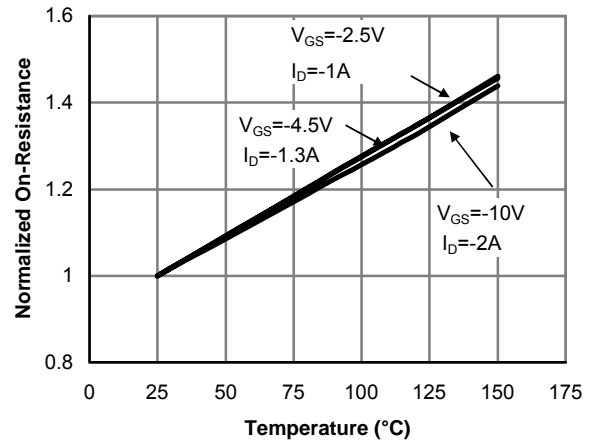


Figure 4: On-Resistance vs. Junction Temperature

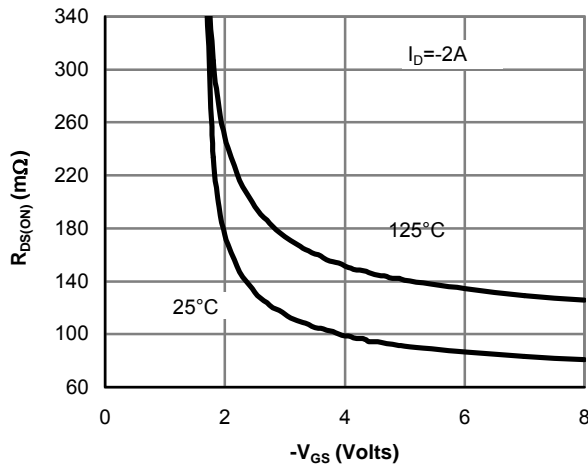


Figure 5: On-Resistance vs. Gate-Source Voltage

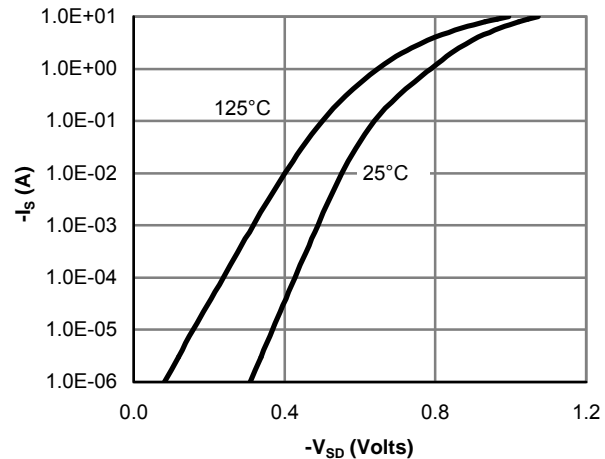


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

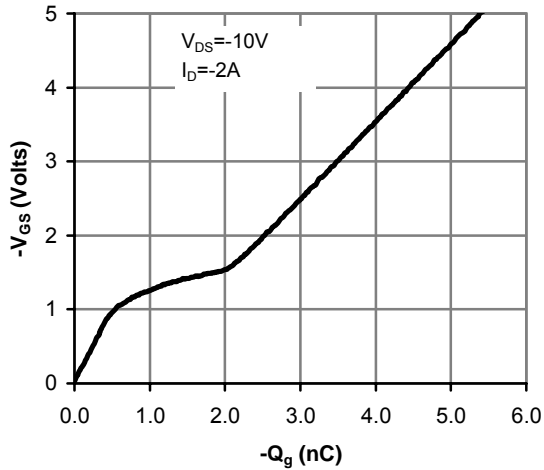


Figure 7: Gate-Charge Characteristics

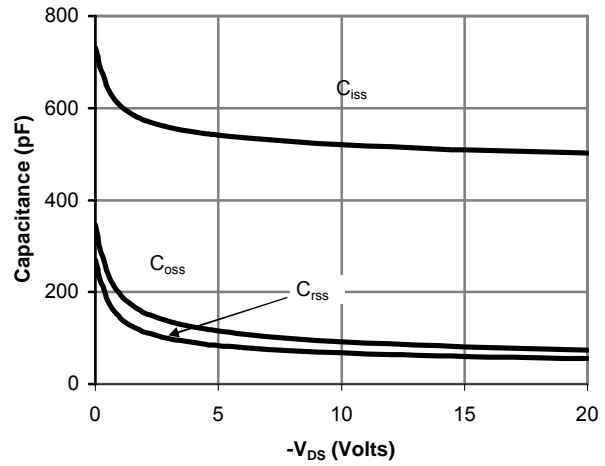


Figure 8: Capacitance Characteristics

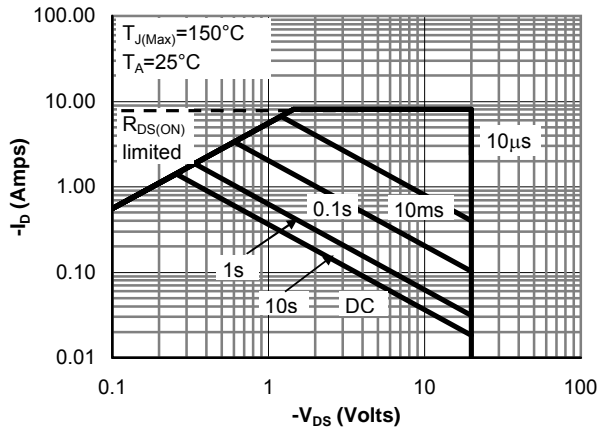


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

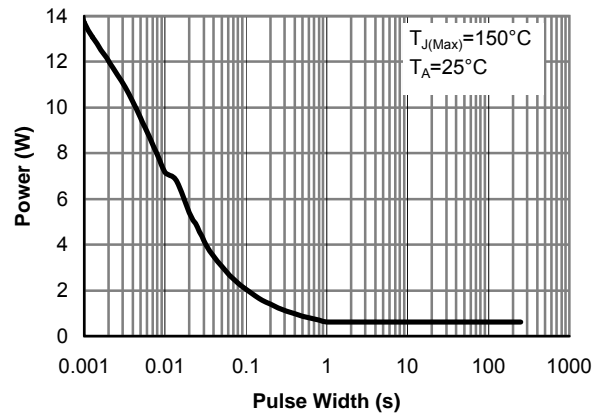


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

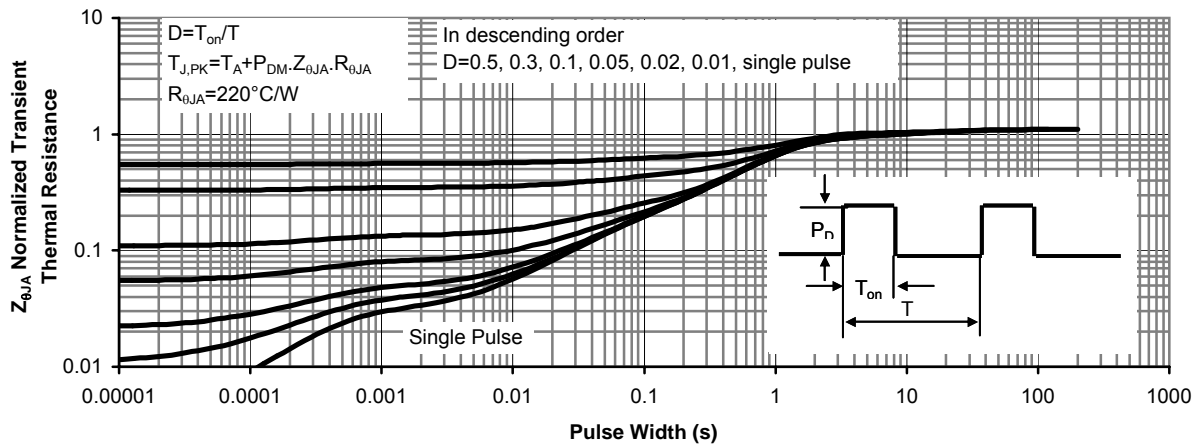
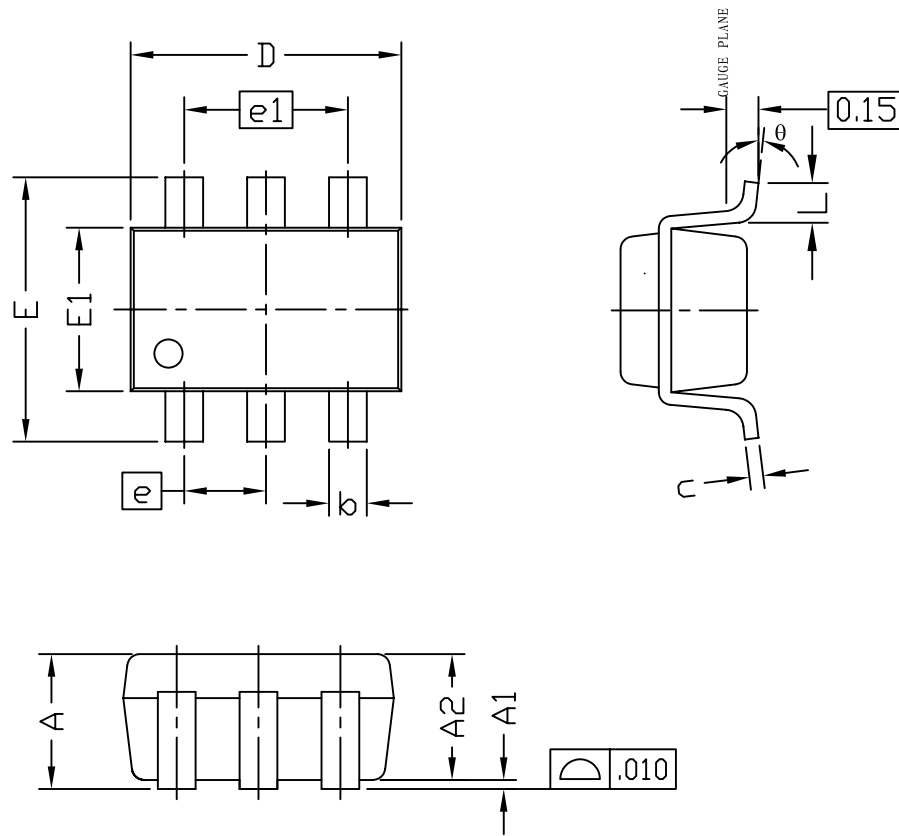


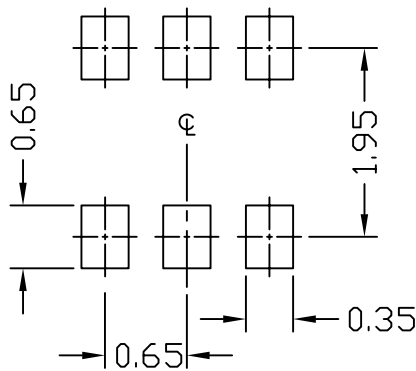
Figure 11: Normalized Maximum Transient Thermal Impedance



SC70-6L PACKAGE OUTLINE



RECOMMENDED LAND PATTERN

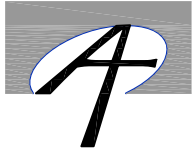


UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A			1.10			0.043
A1	0.00		0.10	0.00		0.004
A2	0.7	0.9	1.00	0.028	0.035	0.039
b	0.15		0.30	0.006		0.012
c	0.08		0.22	0.003		0.009
D	1.85	2.10	2.15	0.073	0.083	0.085
E	1.80	2.30	2.40	0.071	0.091	0.094
e	0.65 BSC			0.026 BSC		
e1	1.30 BSC			0.051 BSC		
E1	1.1	1.30	1.4	0.043	0.051	0.055
L	0.26	0.36	0.46	0.010	0.014	0.018
θ	0°	4°	8°	0°	4°	8°

NOTE

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 3 MILS.
4. DIE IS FACING UP FOR MOLD AND FACING DOWN FOR TRIM/FORM.
ie: REVERSE TRIM/FORM.
5. DIMENSION L IS MEASURED IN GAUGE PLANE.
6. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

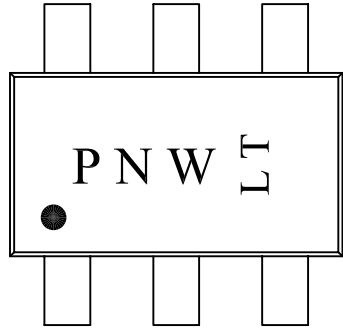


ALPHA & OMEGA

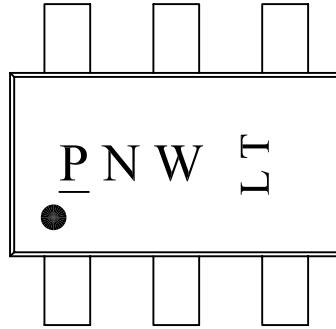
SEMICONDUCTOR, LTD.

Document No.	PD-00324
Version	rev A
Title	AO7415 Marking Description

SC-70(6L) PACKAGE MARKING DESCRIPTION



Standard product



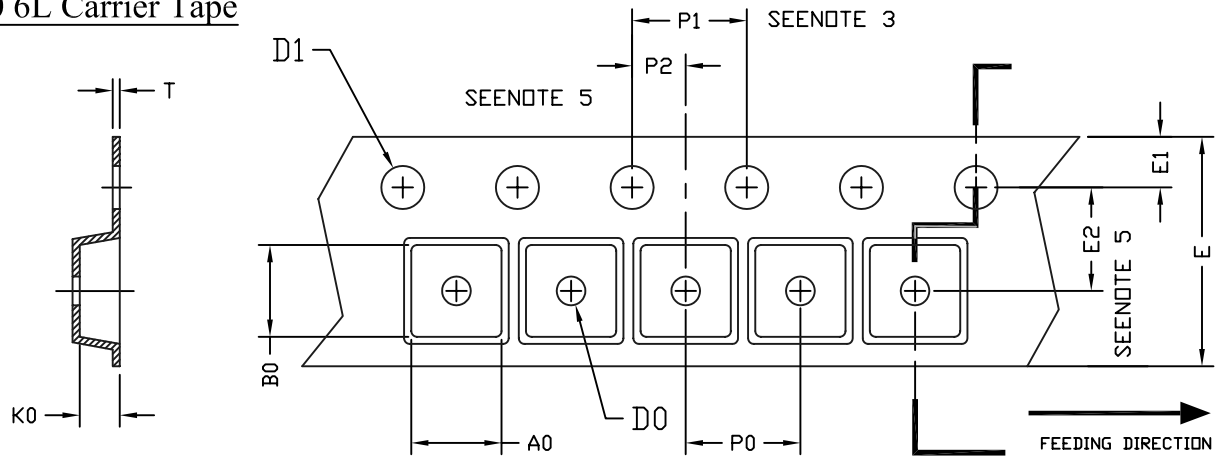
Green product

NOTE:
P - Product number code
N - Assembly location code
W - Year and Week code
L&T - Assembly lot code

PART NO.	DESCRIPTION	CODE (P&N)
AO7415	Standard product	T&N
AO7415L	Green product	<u>T</u> &N



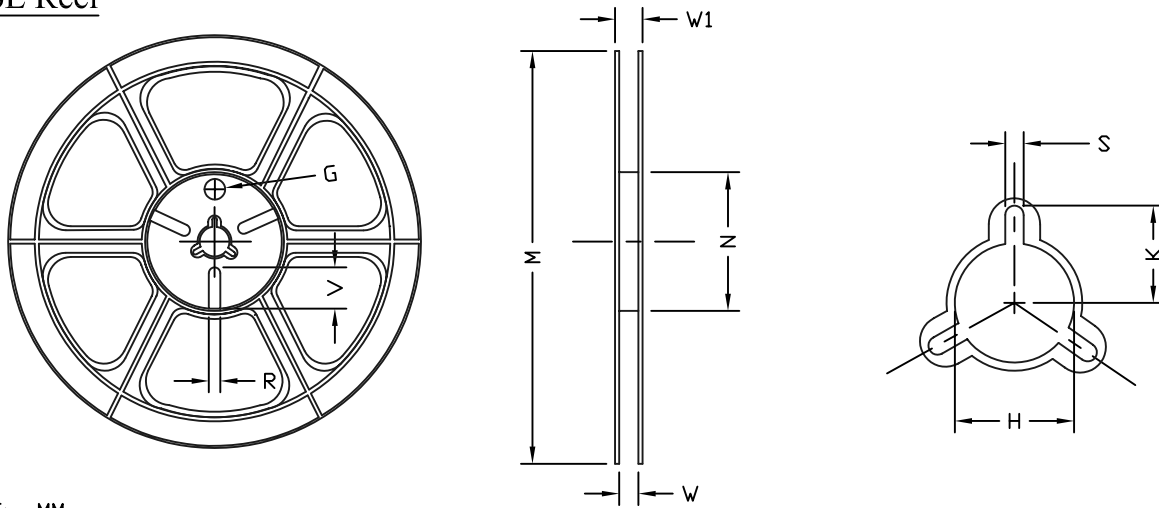
SC-70 6L Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SC-70, 6L (8 mm)	2.40 ±0.10	2.40 ±0.10	1.19 ±0.10	1.00 MIN	1.55 ±0.05	8.00 ±0.30	1.75 ±0.10	3.50 ±0.05	4.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.05

SC-70 6L Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
8 mm	ø180	ø180.00 ±0.50	ø60.50	9.00 ±0.30	11.40 ±1.00	ø13.00 +0.50 -0.20	10.60	2.00 ±0.50	ø9.00	5.00	18.00

SC-70 6L Tape

Leader / Trailer
& Orientation

